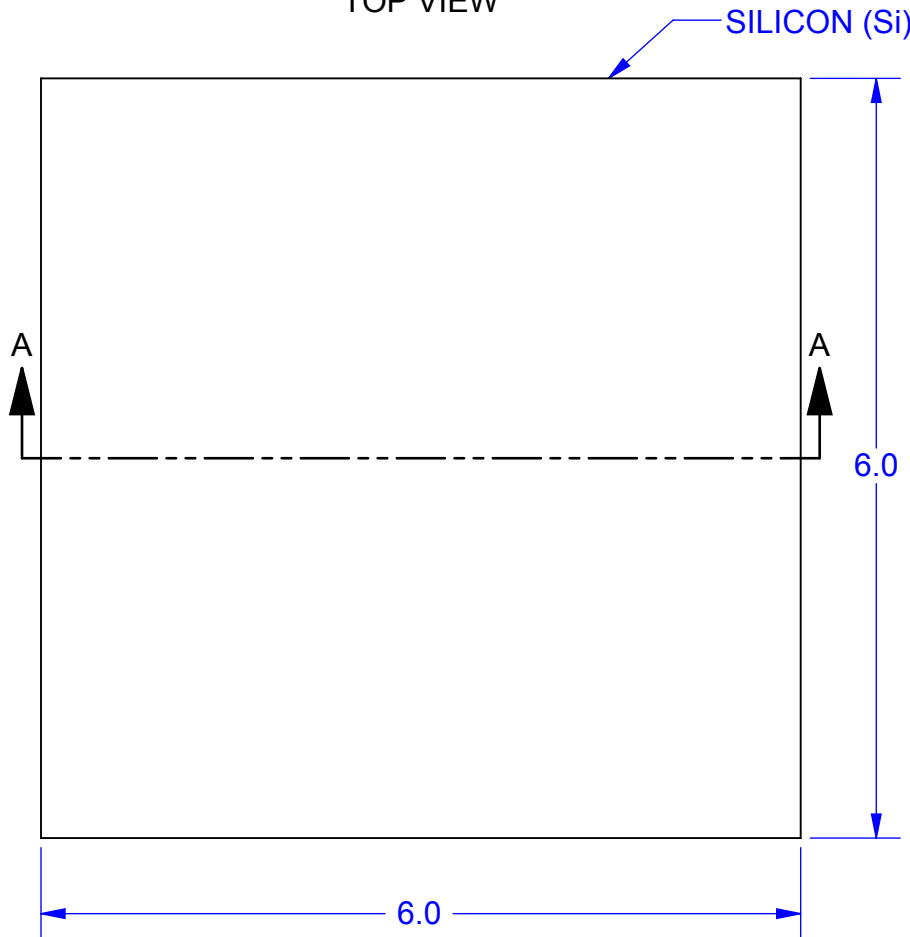
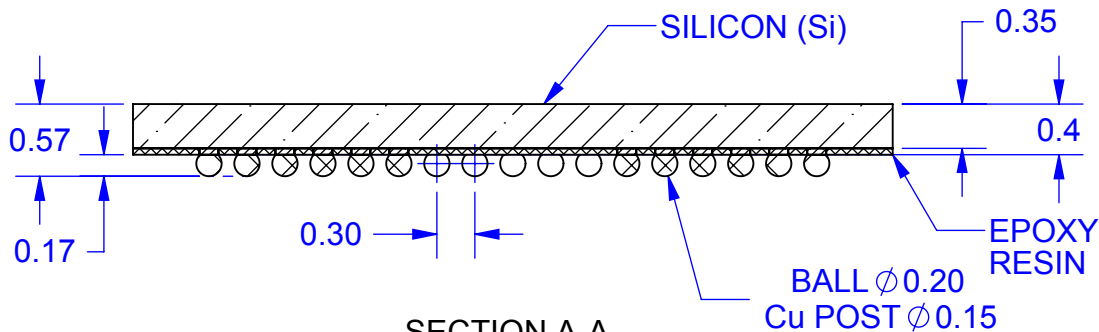
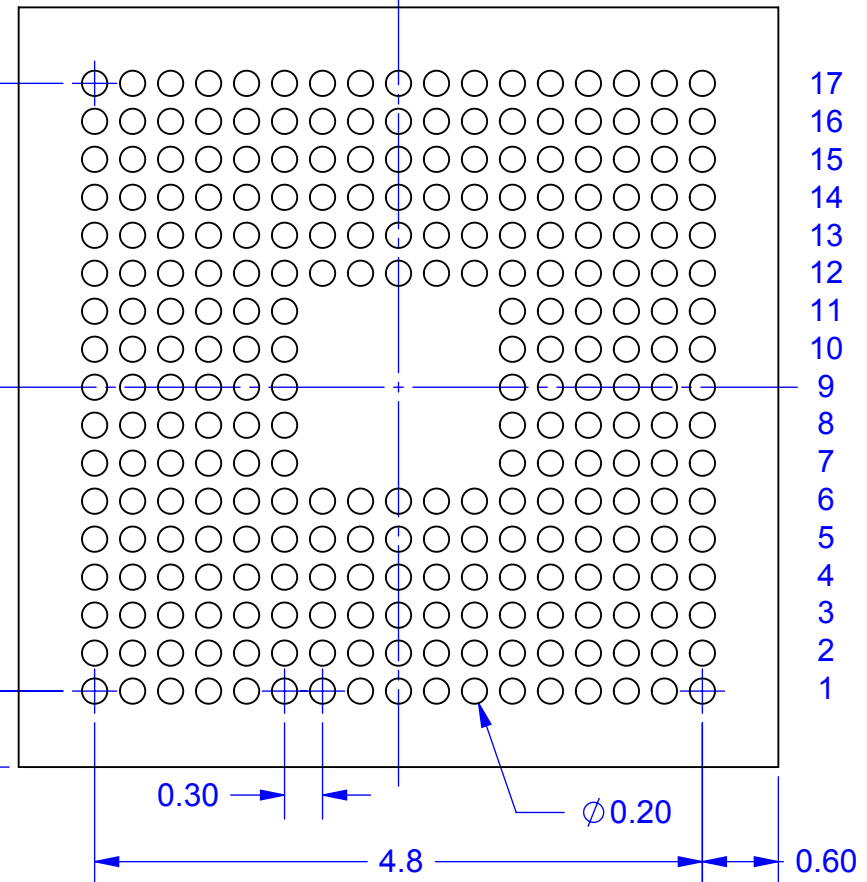


TOP VIEW

BALL VIEW



U T R P N M L K J H G F E D C B A



Notes: (Unless Otherwise Specified).

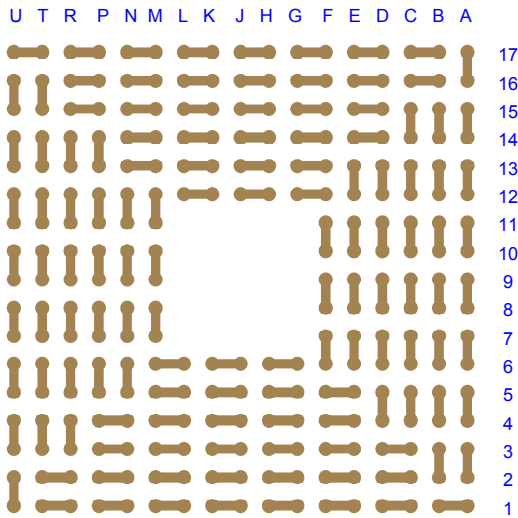
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SAC305 (Sn96.5/Ag3.0/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: 0.20mm.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN IS OMNI-DIRECTIONAL. (SEE PAGE 2)
- 8) PIN A1 MARKING NOT REQUIRED.

SECTION A-A

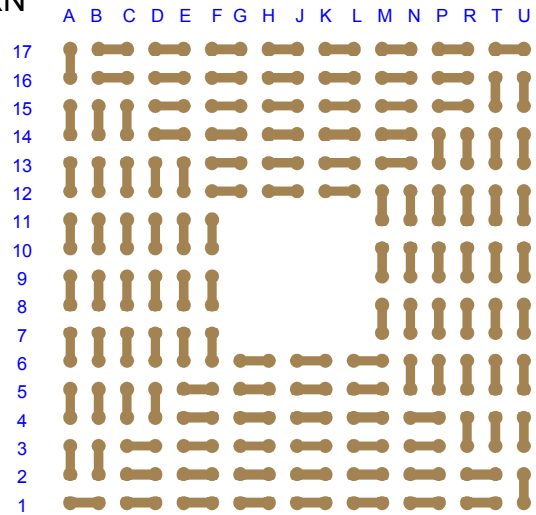
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP264T.3C-DC173D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES

APPROVALS	DATE	TopLine®			
DRAWN T. Au	12/22/12				
ENG M. Hart	12/22/12	TITLE WLP264T.3C-DC173D			
MFG		264-BALL P=0.3mm			
QA		SCALE 16.75:1	SIZE A	DRAWING NO. 531732	REV A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED					

BALL VIEW



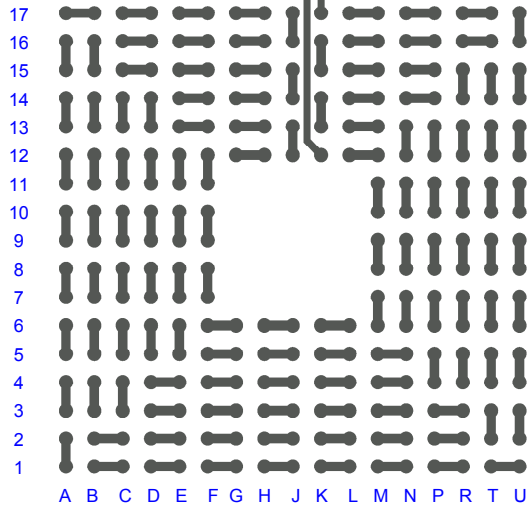
DAISY CHAIN PATTERN



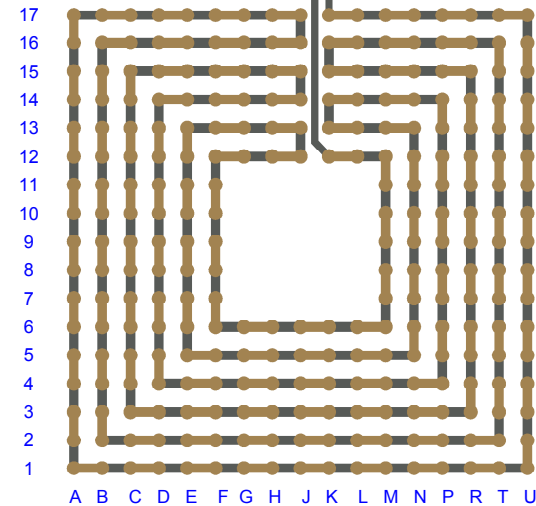
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.15mm (5.9mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).

TopLine®

TITLE			
WLP264T.3C-DC173D 264-BALL P=0.3mm			
SCALE	SIZE	DRAWING NO.	REV
12.5:1	A	531732	A
DO NOT SCALE DRAWING			SHEET 2 OF 2